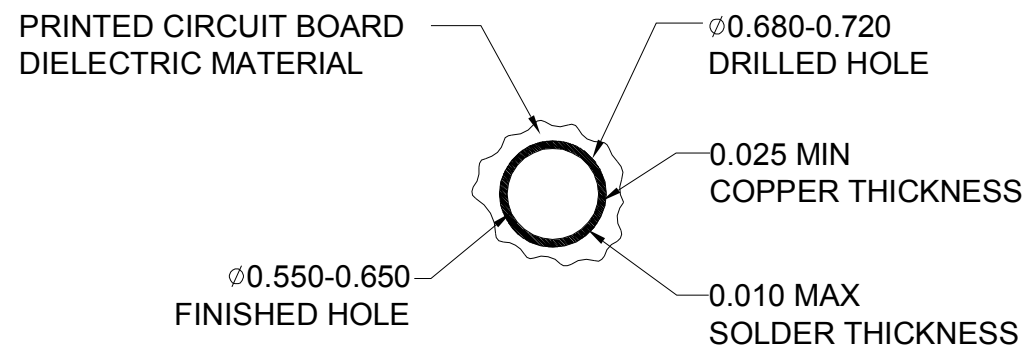
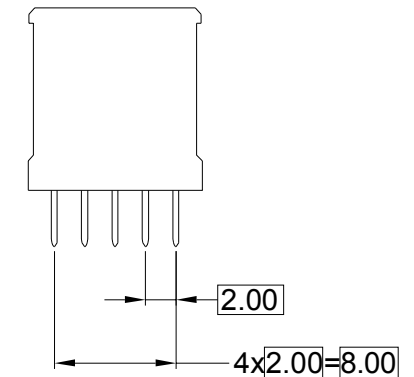
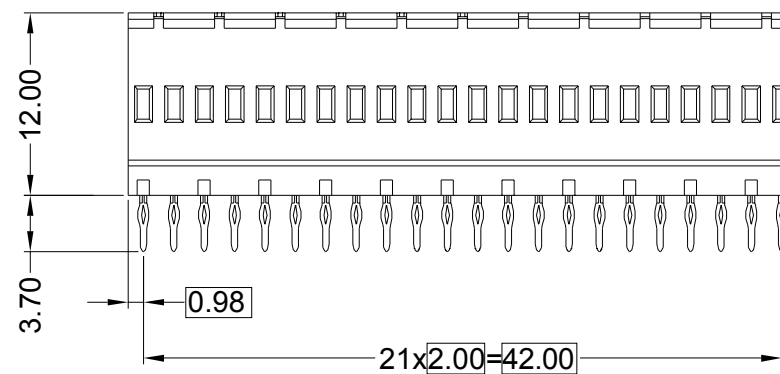
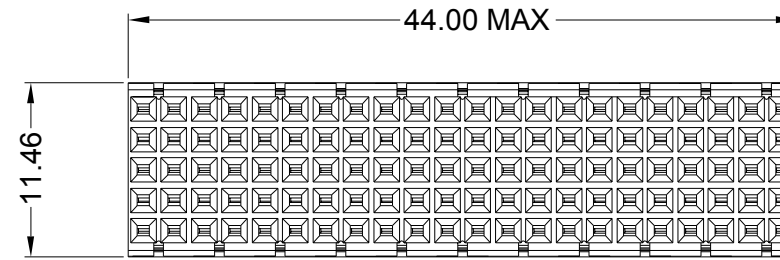
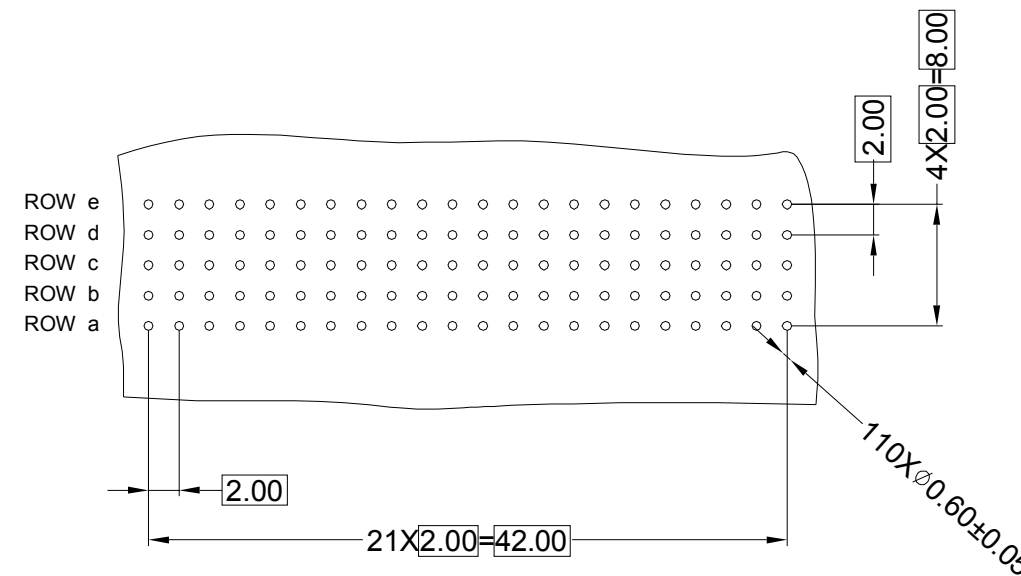


NOTES:

1. ALL DIMENSION ARE IN mm.
2. MATERIAL:
HOUSING: THERMOPLASTIC(94V-0) COLOR: GRAY
CONTACT: COPPER ALLOY
3. FINISH:
CONTACT AREA: GOLD PLATING;
PRESS FIT AREA: MATTE TIN PLATING.
4. ENGAGING AND SEPARATING FORCES PER IEC 61076-4-101.
5. ROHS DIRECTIVE COMPLIANCE.
6. MAX SOLDERING TEMPERATURE 225°C.
7. PERFORMANCE CHARACTERISTICS
INSULATION RESISTANCE: 10,000 MEGOHMS MINIMUM
DIELECTRIC WITHSTANDING VOLTAGE(AT SEA LEVEL): 750 Vrms
CURRENT RATING: 1 AMP AT 70°C, FULLY LOADED
1.5 AMP AT 20°C, FULLY LOADED
OPERATING TEMPERATURE RANGE: -55°C TO +125°C
CONTACT RESISTANCE: 20 MILLIOHMS MAXIMUM



THRU HOLE PLATING
SCALE 10:1



PCB LAYOUT

| | | | | |
|---|--------|---|---|----------|
| DESIGN UNITS ■ mm □ INCH | | NAME: 2MM 180° SOCKET B22 TYPE NO SHIELD | nexttron NEXTRONICS ENGINEERING CORP. | |
| GENERAL TOLERANCES: (UNLESS SPECIFIED) | | PART NO: NX7B0AC01A0AF | TITLE: CUSTOMER DWG | C |
| | mm | INCH | DWG. NO: 010-0000-856-NX7B0AC01A0AF | |
| 4 PLACE | ±.** | ±.** | APPD: 楊海文 5/20'11 | |
| 3 PLACE | ±.** | ±.** | CHKD: 楊海文 5/20'11 | |
| 2 PLACE | ±0.20 | ±.** | DRAWN: 廖小瓊 5/20'11 | |
| 1 PLACE | ±0.30 | ±.** | SCALE: 1/1 | |
| ANGULAR: | X°±.** | .X°±.** | SHEET: 1/1 | REV.: X1 |

| | | | | | |
|------|----------|-------------|---------|-------|------|
| X1 | *** | New Release | 5/20'11 | 廖小瓊 | 楊海文 |
| REV. | ECN. NO. | DESCRIPTION | DATE | DRAWN | APPD |